



Material Declaration Data Sheet

Product: **Server Board SE7520AF2**

Manufacturer: Intel Corporation

Date: October 20 , 2006

Note:

This declaration applies to all associated product codes noted on Page 2

This product and its associated spares and accessories noted on Page 2 comply with the EU RoHS Directive 2002/95/EC.

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

- 1. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- 2. Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 3. Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 4. Lead as an alloying element in copper containing up to 4 % lead by weight.
- 5. Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 6. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7. Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- 8. Lead used in compliant pin connector systems.
- 9. Lead as a coating material for the thermal conduction module c-ring.
- 10. Lead in optical and filter glass.
- 11. Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- 12. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 13. Cadmium in optical and filter glass.
- 14. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- 15. Lead in bronze bearing shells and brushes.
- 16. Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

Product Code Information



Product Code	Description	*RoHS Exemption #
BAF2HPBB	PRODUCT CODE, SE7520AF2, Hot Plug, OEM 10 pack	6
BAF2NSBB	PRODUCT CODE, SE7520AF2, Depop, OEM 10 pack	6
BAF2BB	PRODUCT CODE, SE7520AF2, Non - Hot Plug, OEM 10 pack	6
SC5300AF2	PROD CODE, LX, SE7520AF2, 730W	6
SC5300AF2NA	PROD CODE, LX, SE7520AF2, 730W, NA	6
SE7520AF2	PROD CODE, SE7520AF2, NON HOT-PLUG, BOX	6
SC5300BASE	PROD CODE, BASE, 600W	6
SC5300BASENA	PROD CODE, BASE, 600W, NA	6
SC5300BRP	PROD CODE, BRP, 730W	6
SC5300BRPNA	PROD CODE, BRP, 730W, NA	6
SC5300LX	PROD CODE LX, 730W	6
SC5300LXNA	PROD CODE, LX, 730W, NA	6
AAF2IO	I/O Shield and Gasket	NONE
AXXRAKU42E	Intel® RAID Activation Key kit	6
AXXRPCM1	Intel® Portable Cache Module	6
AXXRIBBU1	Battery back-up unit	6
ARIGHPPCI	Hot plug I/O kit	NONE
AXXIMMPRO	Intel® Server Mgt Mod "Professional Edition"	6
AXXIMMPROBULK	Intel® Server Mgt Mod PRO, OEM	6
AXXIMMADV	Intel Server Mgt Module "Advanced Edition"	6
AXXIMMADV BULK	Intel Server Mgt Mod "Advanced Ed." OEM	6
AXXLCPPED	Intel® Local Control Panel	NONE
ARIGRACK	SC5300 pedestal to rack conversion kit	NONE
ARIGRACKCVR	SC5300 optional unpainted removable side (top) cover	NONE
AXXCMA3U7U	Universal 3U through 7U Rack Mode Cable Management Arm	NONE
AXX04HSBPYCBL	PROD CODE, Y-SCSI CABLE, ROUND	NONE
AXX6SASDB	SC5300 6-drive hot swap SATA/SAS backplane assembly	NONE
AXX4SCSIDB	SC5300 4-drive hot swap SCSI backplane assembly	NONE
AXX6SCSIDB	SC5300 6 drive hot swap SCSI backplane assembly	NONE
AXX4FIXDB	SC5300 cabled 4 drive tool-less drive bay assembly	NONE
AXXFHDDBRK	SC5300 accessory ADAPTER BRACKET	NONE
ARIGDLTRAIL	SC5300 DLT Accessory Kit - left & right rails	NONE
ARIGCDFDBRK	SC5300 5.25" slim-line CD/DVD/Floppy bracket, hardware kit, interface board, installation guide.	6
ARIGHSFANKIT	SC5300 hot swap fan upgrade kit	NONE
ARIGBEZPNL	SC5300 bezel branding panels-	NONE
ARIGPMKIT	SC5300 chassis preventive maintenance kit	6
FXX600WPSU	SC5300 Base / SC5275-E 600W PS	NONE
FXX730WPSU	SC5300LX/BRP 730W Power Supply Module and power supply filler panel.	NONE

FRIGHSFANS	SC5300LX hot swap fan spare kit	NONE
FRIGFIXFANS	SC5300 non hot swap fan spare kit	NONE
FXX6SASBRD	SC5300 / SC5275-E 6 Drive SATA/SAS Backplane Board only	6
FXX4SCSIBRD	SC5300 4 Drive SCSI Backplane Board only	6
FXX6SCSIBRD	SC5300 / SC5275-E 6 Drive SCSI Backplane Board only	6
FRIGPDB	SC5300LX Power Distribution board	NONE
PWRCABLEUS	North American AC power cord	NONE
AXXSCD	Slim-line CD drive	NONE
AXXSFLOPPY	Slim-line Floppy drive	NONE
AXXDVDCDR	Slim-line DVD/CDR drive	NONE
FXX2DRVCARBLK	Hot swap drive carrier spare. MOQ = 10	NONE
SRCU42E	Intel® RAID Controller SRCU42E	6
SRCU42EBLK	Intel® RAID Controller SRCU42EBLK	6
SRCU42X	Intel® RAID Controller SRCU42X	6
SRCS16	Intel® RAID Controller SRCS16	6
SRCS28X	Intel® RAID Controller SRCS28X	6

* RoHS Exemption # corresponds with exemption #'s found on page 1.